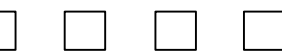


MU147-1



颜色 (主体)

- 1: 黑色
- 2: 白色
- 3: 贝吉色
- 4: 灰色
- 5: 蓝色
- 6: 绿色
- 7: 红色
- 0: 其它

材质 (主体)

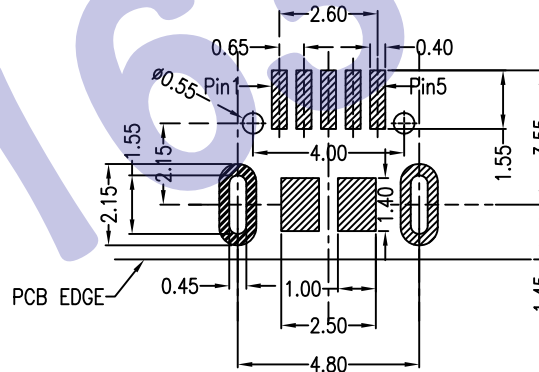
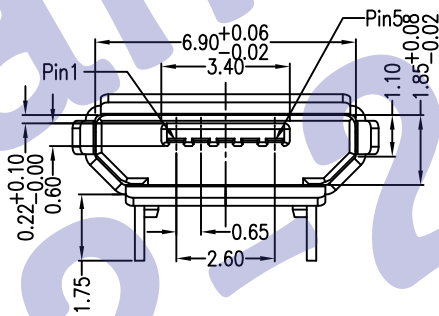
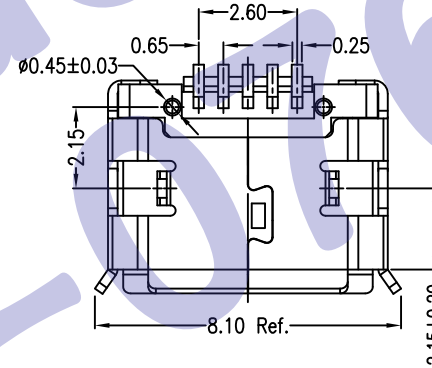
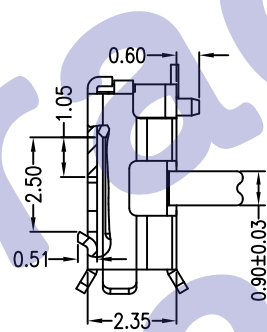
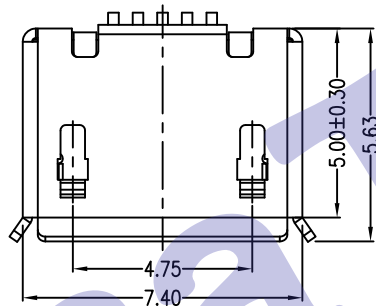
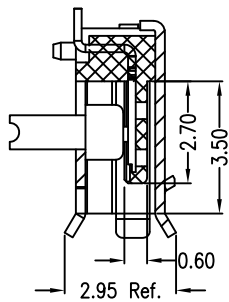
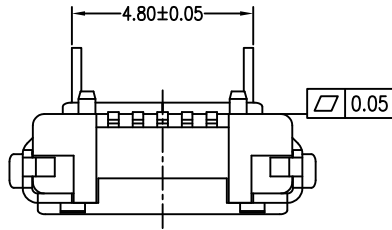
- 1: PBT
- 3: NL9T
- 5: ABS
- 7: PPS
- 9: PE
- 0: 其它
- 2: LCP
- 4: NL6T
- 6: NL66
- 8: PVC

外壳镀层

- 1: 全金
- 2: 全镍
- 3: 全锡
- 4: 前金后锡
- 5: 前金后镍
- 6: 前镍后锡
- 0: 其它

端子镀层 (接合处)

- 1: 1U"
- 2: 3U"
- 3: 5U"
- 4: 10U"
- 5: 15U"
- 6: 30U"
- 0: 其它



RECOMMENDED PCB LAYOUT

Note:

1. Material:

1.1 Housing: High temperature thermoplastic with g.f, UL94v-0

1.2 Contact: copper alloy, t=0.20mm

1.3 Shell: copper alloy, t=0.25mm

2. Specification:

2.1 Current rating: 1 A Max.

2.2 Dielectric withstanding voltage: 100 V(ac) for 1 min.

2.3 Contact resistance: 50 mΩ Max.

2.4 Insulation resistance: 100 MΩ Min.

2.5 Total mating force: 3.57 Kgf Max.

2.6 Total unmating force: 1.0 Kgf Min.0.81~2.05 A Kgf Min.after 10000 insertion/extraction cycles

2.7 Temperature range: -30°C~80°C

设计 DRAW BY	杨帆	审核 DISCUSS BY		图名 DRAWING NO	MICRO USB B TYPEDIP 4.8 DIP 有柱 加长0.4针	图号 SHEET NO	147-1	日期 DATE	2011.5.20
校对 DISCUSS BY		比例 SCALE	2:1	客户 VERSION		数量 QUAN		备注 REMARK	
HDC有限公司				数量 QUAN		备注 REMARK		版次 REMARK	
				张号 SHEET	1/1				